



MUSB, MUSBR, UUSB SERIES

MINI & MICRO USB 2.0 INTERFACES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MUSB or www.samtec.com?MUSBR

Insulator Material: High Temperature Thermoplastic
Contact Material: Phosphor Bronze
Shell Material: Brass
Plating: Gold on Mating Area, Nickel on Shell, Tin on Tails
Operating Temp Range: -50°C to +85°C
Current Rating: 1A per contact
Voltage Rating: 30 VRMS
Contact Resistance: 50 mΩ max
Minimum Cycles: 1500
Packaging: Packaged and shipped in Bulk Packaging Trays; Trays suitable for automation are available upon request.
RoHS Compliant: Yes
Lead-Free Solderable: Yes

TYPE	NO. OF CONTACTS	PLATING	COLOR	TYPE	SM	A
MUSB = Mini USB 2.0	-05	-F = Gold Flash on Mating Area, Tin on Tails	-O = Orange	-B = B Type (MUSB & MUSBR)		
MUSBR = High Retention Mini USB 2.0		-S = 30μ" (0,76μm) Gold on Mating Area, Tin on Tails		-AB = AB Type (MUSB only)		
				-A = A Type (MUSBR only)		

ALSO AVAILABLE
Mini USB-A Type. Call Samtec.

RUGGEDIZED by SAMTEC
• High retention option

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?UUSB

Insulator Material: Black LCP
Contact Material: Phosphor Copper
Plating: Au over 50μ" (1,27μm) Ni
Shield Plating: Sn over 50μ" (1,27μm) Ni
Operating Temp Range: -30°C to +80°C
Current Rating: 1A (pin 2, 3, 4) per signal contact, 1.8A (pin 1, 5) per power contact
Voltage Rating: 100 VAC
Contact Resistance: 50 mΩ max
Cycles: 10,000
RoHS Compliant: Yes

UUSB	TYPE	S	PLATING	TERMINATION	TR
UUSB = Micro USB 2.0	-AB = Micro AB		-F = Gold Flash on Mating Area and Tails	-SM = Surface Mount	-TR = Tape & Reel
	-B = Micro B		-S = 30μ" (0,76 μm) Gold on Mating Area, Gold Flash on Tails		

PRELIMINARY

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM